

# PICO-APL4

BIOS/PL1 : Disable (Power TDP: 15W)

## Thermal Image Analysis Report

**Test Cause**

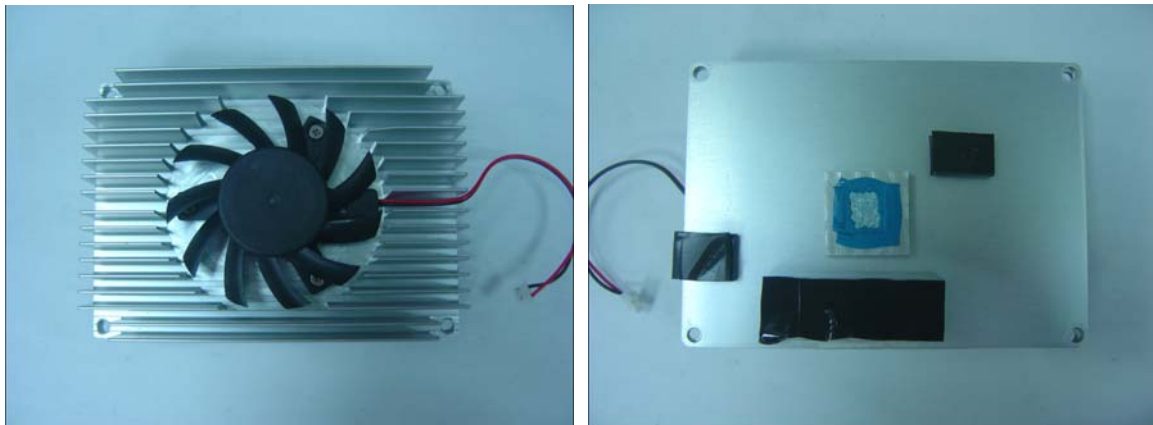
**For ATRF No.QE180202 Request**

Summary	<input type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input checked="" type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> <u>There are one temperature point marginal passed, the system works properly.</u>			
<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date	QE Manager	Test Engineer
2018 / 06 / 21	KJ Wang	Juno Cheng

## Sample Configuration & Quantity Under Test

- **Model name : PICO-APL4 A0.3**
- **CPU : Intel® Pentium® Processor N4200**
- **Memory : Onboard memory DDR3L-1600 4GB**
- **Storage : eMMC 32GB**
- **BIOS :PICO-APL4 R1.1 ( ZAP4AM11)(05/14/2018)**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro(1025)**
- **Power : FSP040-DHAN3(Output: 12V,3.3A)**
- **CPU Cooler :**



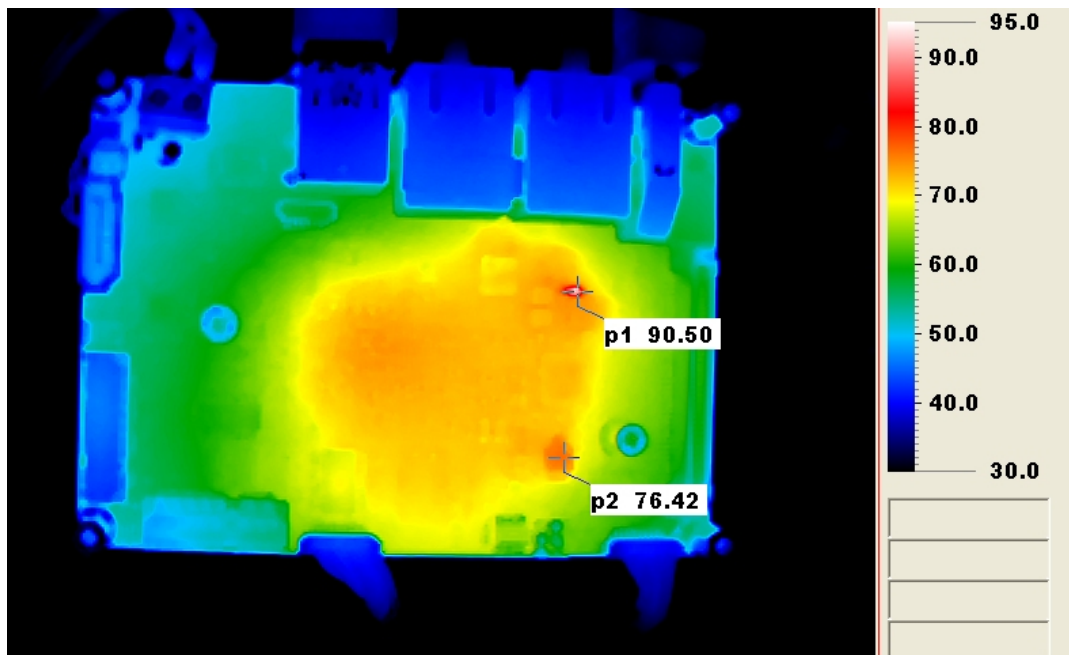
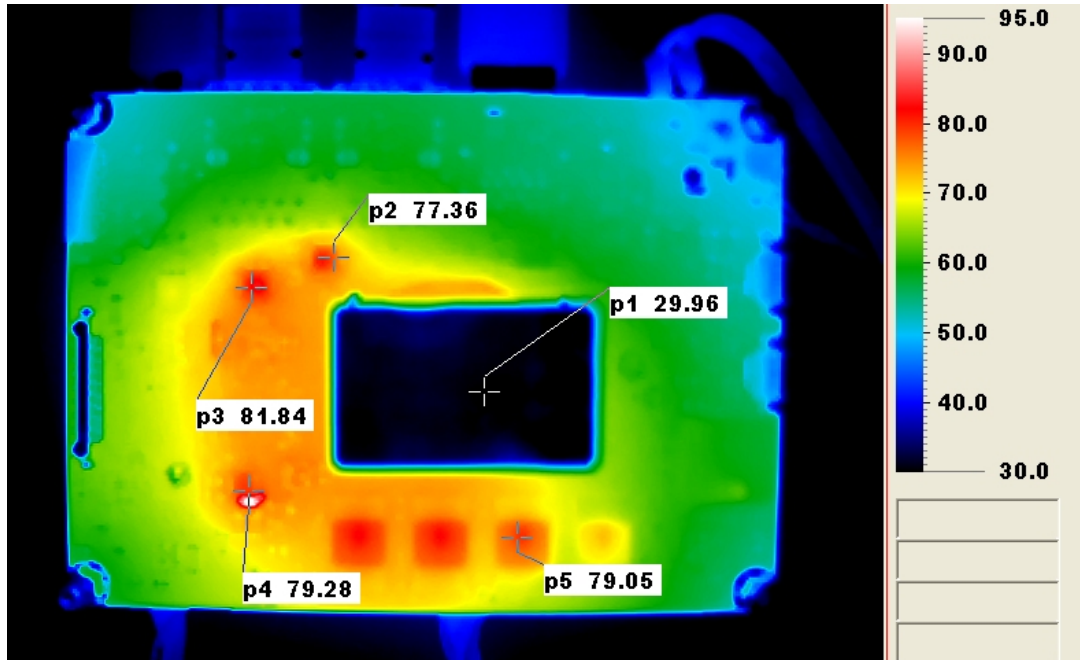
# Thermal Image Analysis

1. Test Date: 2018-06-21
2. Test Product: PICO-APL4 A0.3
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
  - 4.1. 40 Channel Thermal Recorder:
    - 4.1.1 YOKOGAWA Inc,
    - 4.2.2 Model: DA100-13-1D  
Date of Calibration: 2017/09/08  
Serial Number: 12A323190
  - 4.2. IR Scanner: Infrared Camera
    - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
    - 4.2.2 Model: Thermo GEAR G100W2-D  
Date of Calibration: 2017/11/23  
Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.2°C with Heat Sink + Fan (Full Speed)
6. Take Picture Time:

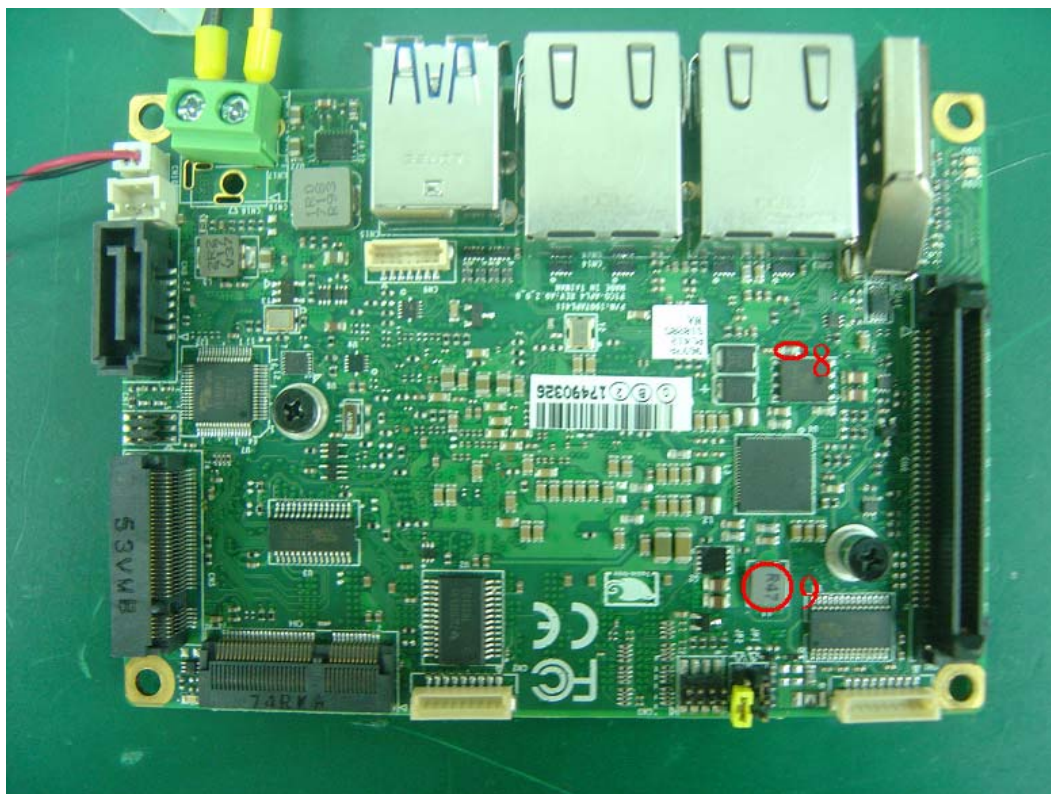
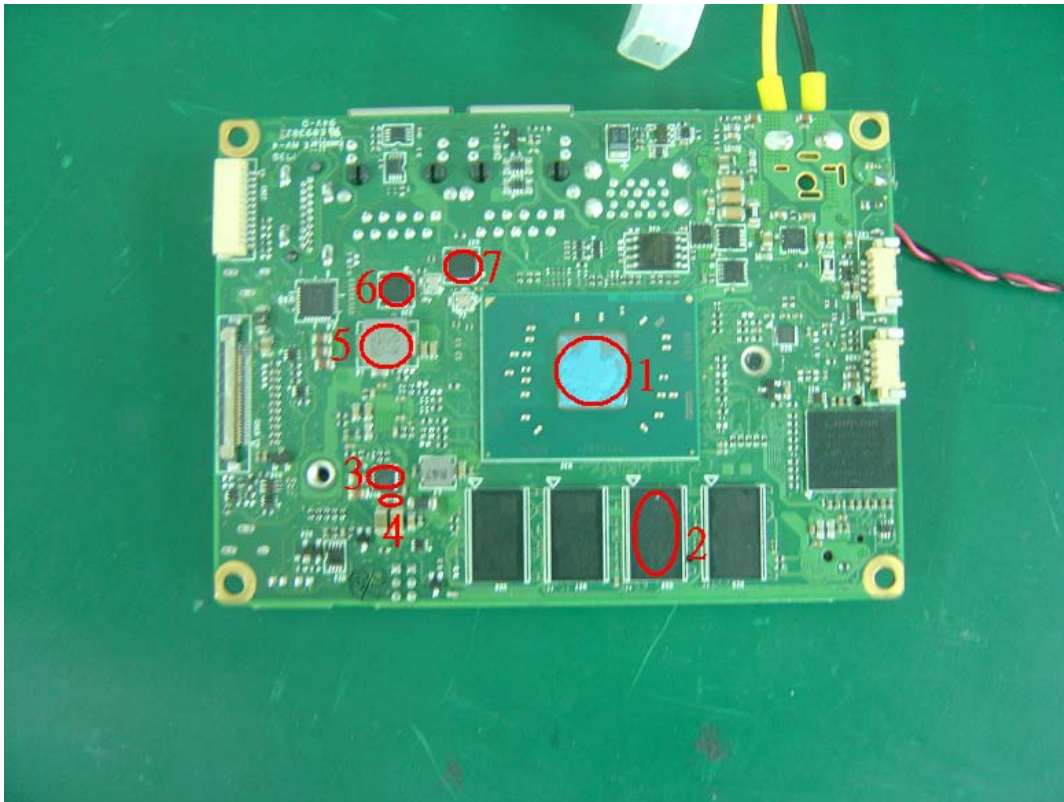
After power on 2 hours

### Temperature Profile Test: Component Side:



**Terminal Recorder:**

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				25.0°C	60°C		
1	U32	(TF)INTEL CPU.Apollo Lake.Pentium N4200.2.5GHz FCBGA1296 SMD FH8066802979703.SR2Z5	105	43.0	78.0		
2	U26	(TF)IC.DDR3L-SDRAM.512Mx16(bit).Dual-Die.1600MHz.1. 35V.FBGA.96P.SMD.Samsung.K4B8G1646D-MYK0	95	38.8	73.8		
3	Q18	(TF)PWR.PMPAK3X3 DUAL N-MOSFET.Vgs1/2=(+/-)20V Id1=6A.SMD.FAIRCHILD.FDMC7200S.Id2=8.5A.Vds1/2=30 V	125	62.2	97.2		
4	R252	(TF)CR.2.2.1/10W.1%.0603.SMD	125	65.8	100.8		
5	L8	(TF)COIL.0.22uH.DCR=2.8mohm.Idc=23Amp.20%.SMD.6. 95x6.6x2.8mm.CYNTEC.PCMB063T-R22MS	125	73.8	108.8		
6	U36	(TF)IC.PCI-express.Gigabit Ethernet Chip.QFN 32P.SMD.REALTEK.RTL8111G-CG	100	57.9	92.9		
7	U37	(TF)IC.PCI-express.Gigabit Ethernet Chip.QFN 32P.SMD.REALTEK.RTL8111G-CG	100	51.8	86.8		
8	R138	(TF)CR.2.2.1/10W.1%.0603.SMD	125	68.8	103.8		
9	L1	(TF)Coil.0.47uH.DCR=14mΩ.Irms=7Amp.20%.4.5x4x1.8m m.SMD.GOTREND.GSTD4020PE-R47M	125	65.1	100.1		

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "TAT" indicates the actual measured temperature under product specification.
- "TPT" indicates the predicted temperature under 25°C working environmental.
- Judgment Criteria:**
  - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
  - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
  - **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.
- RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
- Defect NO.**